Texas Instruments

TI DESIGNS

Bill of Materials

Designator	Value and Description	Quantity	Manufacturer	MFG Part Number
C1, C2, C4, C5	CAP CER 0.1UF 25V 10% X7R 0603	4	Yageo	CC0603KRX7R8BB104
C1_1, C1_2	CAP CER 10UF 50V 20% X5R 1206	2	Taiyo Yuden	UMK316BBJ106ML-T
C2_1, C2_2	CAP CER 0.1UF 50V Y5V 0603	2	Yageo	CC0603ZRY5V9BB104
C3	CAP ALUM 10UF 25V 20% RADIAL	1	Nichicon	UVR1E100MDD
C6, C7	CAP CER 33PF 16V 5% X7R 0603	2	AVX Corporation	0603YC330JAT2A
CLK, DIN, DOUT1, DOUT2, ENAB LE, LATCH, nFAULT1, nFAULT2, V3P3	TEST POINT PC COMPACT .063"D WHT	9	Keystone Electronics	5007
GND1, GND2, GND3, GND4	TEST POINT PC COMPACT .063"D BLK	4	Keystone Electronics	5006
D1, D2, D3, D4, D5	LED RED FACE UP 1206	5	Panasonic Electronic	LNJ211R82RA
D1_1	LED RED FACE UP 1206	1	Panasonic Electronic	LNJ211R82RA
D1_2	LED RED FACE UP 1206	1	Panasonic Electronic	LNJ211R82RA
D6, D7, D8, D9, D10, D11, D12, D13, D14, D15, D16, D17, D18, D19, D20, D21	LED RED FACE UP 1206	16	Panasonic Electronic	LNJ211R82RA
GPIO	CONN HEADER .100 SNGL STR 5POS	1	3M	929647-09-05-I
J1	CONN HEADER .100 SNGL STR 3POS	1	3M	929647-09-03-I
J2	CONN HEADER .100 SNGL STR 3POS	1	3M	929647-09-03-I
J_USB	CONN RCPT MICRO USB TYPE AB	1	TE Connectivity	1981584-1
L1	FERRITE CHIP 100 OHM 1A 0603	1	TDK Corporation	MPZ1608D101B
P1	CONN HEADER .100 DUAL STR 14POS	1	3M	929665-09-07-I
P_DRV_1, P_DRV_2, P_IN_1, P_IN_2	CONN HEADER .100 DUAL STR 16POS	4	3M	929665-09-08-I
P_GND, P_GND_1, P_GND_2, P_VM_1, P_VM_2, P_VM_IN, P_VM_OUT	CONN HEADER .100 SNGL STR 4POS	7	3M	929647-09-04-I
P_OUT_1, P_OUT_2	CONN HEADER .100 SNGL STR 8POS	2	3M	929647-09-08-I
Q1	MOSFET P-CH 40V SOT-23	1	Vishay Siliconix	SI2319CDS-T1-GE3
Q2	TRANS NPN 40V 350MW SMD SOT23-3	1	Diodes Inc	MMBT3904-7-F
R1	RES 3.3K OHM 1/10W 5% 0603 SMD	1	Panasonic Electronic	ERJ-3GEYJ332V
R1_1, R1_2	RES 330 OHM 1/10W 5% 0603 SMD	2	Panasonic Electronic	ERJ-3GEYJ331V
R2, R3, R4, R5, R6	RES 330 OHM 1/10W 5% 0603 SMD	5	Panasonic Electronic	ERJ-3GEYJ331V
R7, R8, R9, R10, R11, R12, R13, R14, R15, R16, R17, R18, R19, R20, R21, R22	RES 10K OHM 1/10W 5% 0603 SMD	16	Panasonic Electronic	ERJ-3GEYJ103V
R23, R24, R25, R26, R27, R28, R29, R30, R31, R32, R33, R34, R35, R36, R37, R38	RES 27K OHM 1/10W 5% 0603 SMD	16	Panasonic Electronic	ERJ-3GEYJ273V
R39, R40	RES 10K OHM 1/10W 5% 0603 SMD	2	Panasonic Electronic	ERJ-3GEYJ103V
R41	RES 22K OHM 1/10W 5% 0603 SMD	1	Panasonic Electronic	ERJ-3GEYJ223V
SW_RST, SWA, SWB, SWC, SWD	SWITCH TACTILE SPST-NO 0.05A 24V	5	Omron Electronics	B3F-1000
U1	IC MCU 16BIT 16KB FLASH 40VQFN	1	Texas Instruments	MSP430F2350TRHAT
U2	IC USB FS SERIAL UART 28-SSOP	1	FTDI	FT232RL R
U2_1, U2_2	(Supplied) 8 Channel Serial Interface Low-Side Driver	2	Texas Instruments	DRV8860PW
U3	IC ESD-PROT ARRAY 2CH 6-SON	1	Texas Instruments	TPD2E001DRYR
Y1	CRYSTAL 8.00 MHZ 20PF 49US	1	ECS Inc.	ECS-80-20-4X

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